ASSOCIATION CON ELECTRONICS IND	© Copyright 2005.	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.		der both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				ials and Mfc Information				
upplier In	formation	,							,					
Company name*			Company unique ID			J	Unique ID Authority				Response Date*			
nsemi										2024-05-16				
Contact Name			Title - Contact			I	Phone - Contact*				Email - Contact*			
Product-Env-	Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
uthorized Re	epresentative*	Title - Representative			I	Phone - Representative*				Email - Representative*				
Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
Re	equester Item Number	Mfr Item	•	Mfr Item Name			Effective Date	Version	N	Ianufacturing Site	W	eight*	UOM	Unit Type
		FDMS004N08C FET 80V 4.0 mC		FET 80V 4.0 mOhr	n PQFN56		2024-05-16 PBB		ВВ	10	09.07974	mg	Each	
	ring Process Informa				OZED 020 1401		D 1 D	D 1 T		M. Ti . D. I		la.	S.D. Cl. Cl.	,
2		,		STD-020 MSI	_ Rating	Peak Process Body Temper						r of Reflow Cyc	eles	
•	tte Tin (Sn) - annealed	C	CU Alloy	1			260		C	30	second	s 3		
omments														
	num time at peak temperat													
r more info	rmation regarding materia	l composition	please refer t	o page 3										

RoHS Material Composition Declaration			Declaration Type *	Detailed						
irective 2015/863/EU amending RoHS irective 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Itability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to suc										
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature Ra	astislav Drska	-En								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	14.9856	mg	Supplier	Zinc (Zn)	7440-66-6		0.018	mg
			Supplier	Iron (Fe)	7439-89-6		0.3522	mg
			Supplier	Copper (Cu)	7440-50-8		14.611	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0045	mg
Die	2.6048	mg	Supplier	Silicon (Si)	7440-21-3		2.6048	mg
Die Attach Solder	4.2978	mg	Supplier	Silver (Ag)	7440-22-4		0.1074	mg
			A	Lead (Pb)	7439-92-1	7a	3.9755	mg
			Supplier	Tin (Sn)	7440-31-5		0.2149	mg
Lead Frame	45.3136	mg	Supplier	Silver (Ag)	7440-22-4		2.2657	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0544	mg
			Supplier	Iron (Fe)	7439-89-6		1.0875	mg
			Supplier	Copper (Cu)	7440-50-8		41.8698	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0363	mg
Mold Compound-Black	39.5381	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		2.57	mg
			Supplier	Carbon Black (C)	1333-86-4		0.1977	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		34.7935	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		1.9769	mg
Plating	2.33184	mg	Supplier	Tin (Sn)	7440-31-5		2.3318	mg
Wire Bond - Cu	0.008	mg	Supplier	Palladium (Pd)	7440-05-3		0.0002	mg
			Supplier	Copper (Cu)	7440-50-8		0.0078	mg